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Boeckel et al.

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(54) **HEADPHONE**

(71) Applicant: **Koninklijke Philips N.V.**, Eindhoven (NL)

(72) Inventors: **Peter A. Boeckel**, Hong Kong (CN);
Billy Liu, Hong Kong (CN)

(73) Assignee: **Koninklijke Philips N.V.**, Eindhoven (NL)

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(52) **U.S. Cl.**
USPC **D14/205**

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See application file for complete search history.

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Primary Examiner — Paula Greene

(74) *Attorney, Agent, or Firm* — Venable LLP; Steven J. Schwarz

(57) **CLAIM**

The ornamental design for headphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a headphone according to an embodiment of the claimed design;
FIG. 2 is a front elevational view of the headphone of FIG. 1;
FIG. 3 is a rear elevational view of the headphone of FIG. 1;
FIG. 4 is a left elevational view of the headphone of FIG. 1;
FIG. 5 is a right elevational view of the headphone of FIG. 1;
FIG. 6 is a top elevational view of the headphone of FIG. 1; and,
FIG. 7 is a bottom elevational view of the headphone of FIG. 1.
The features shown in broken lines are environment only and not part of the claimed design.

1 Claim, 5 Drawing Sheets



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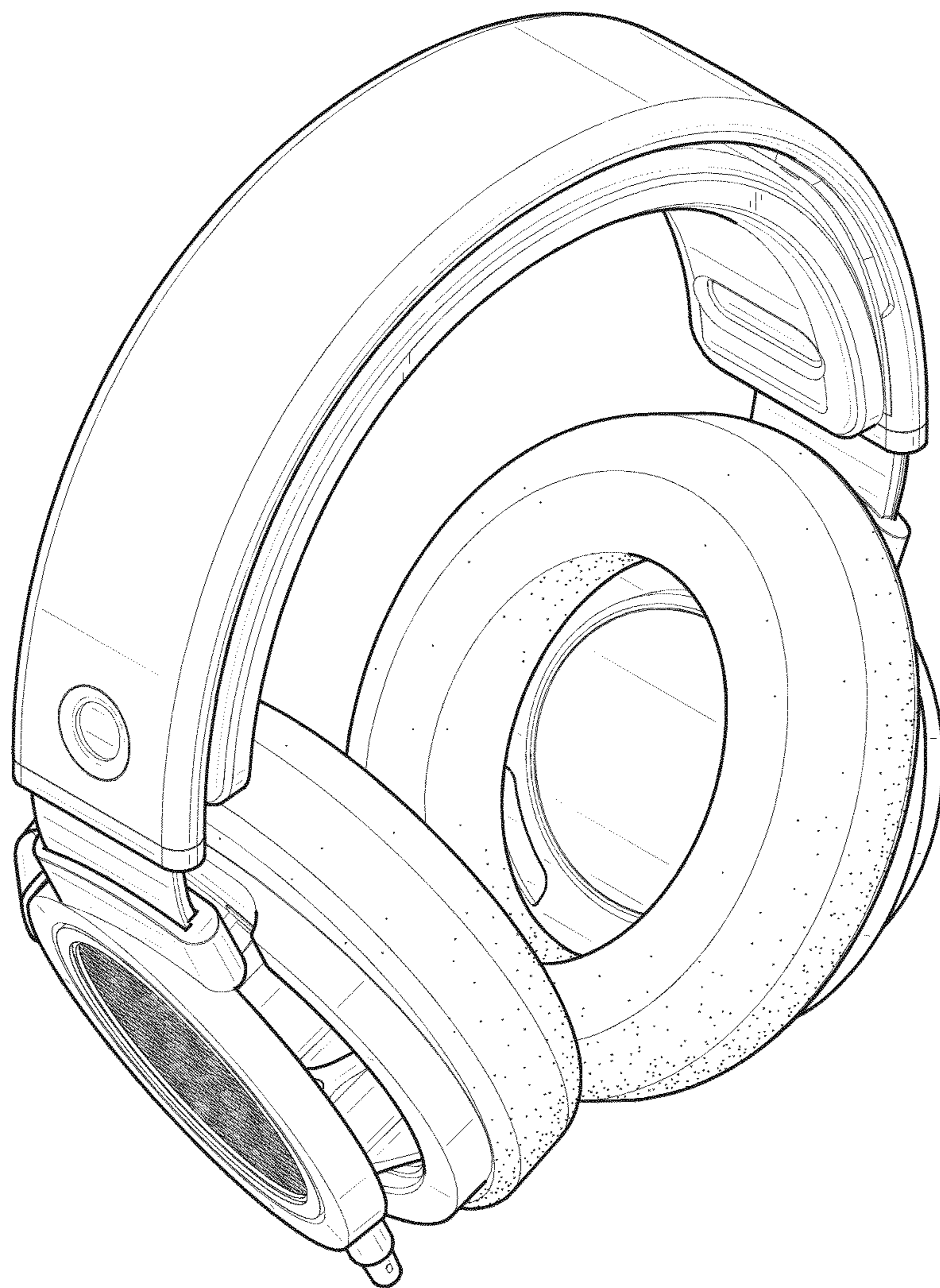


FIG. 1

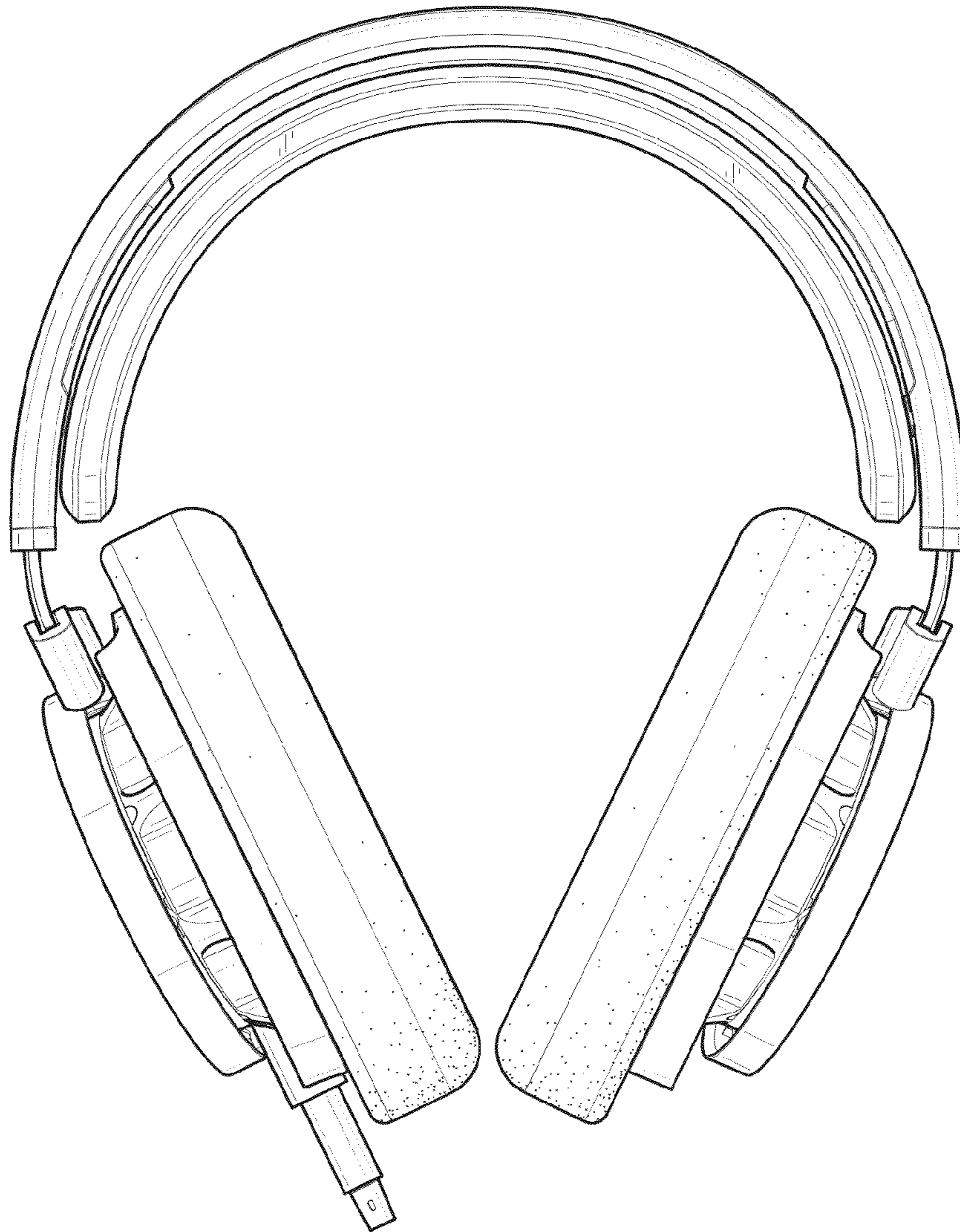


FIG. 2



FIG. 3

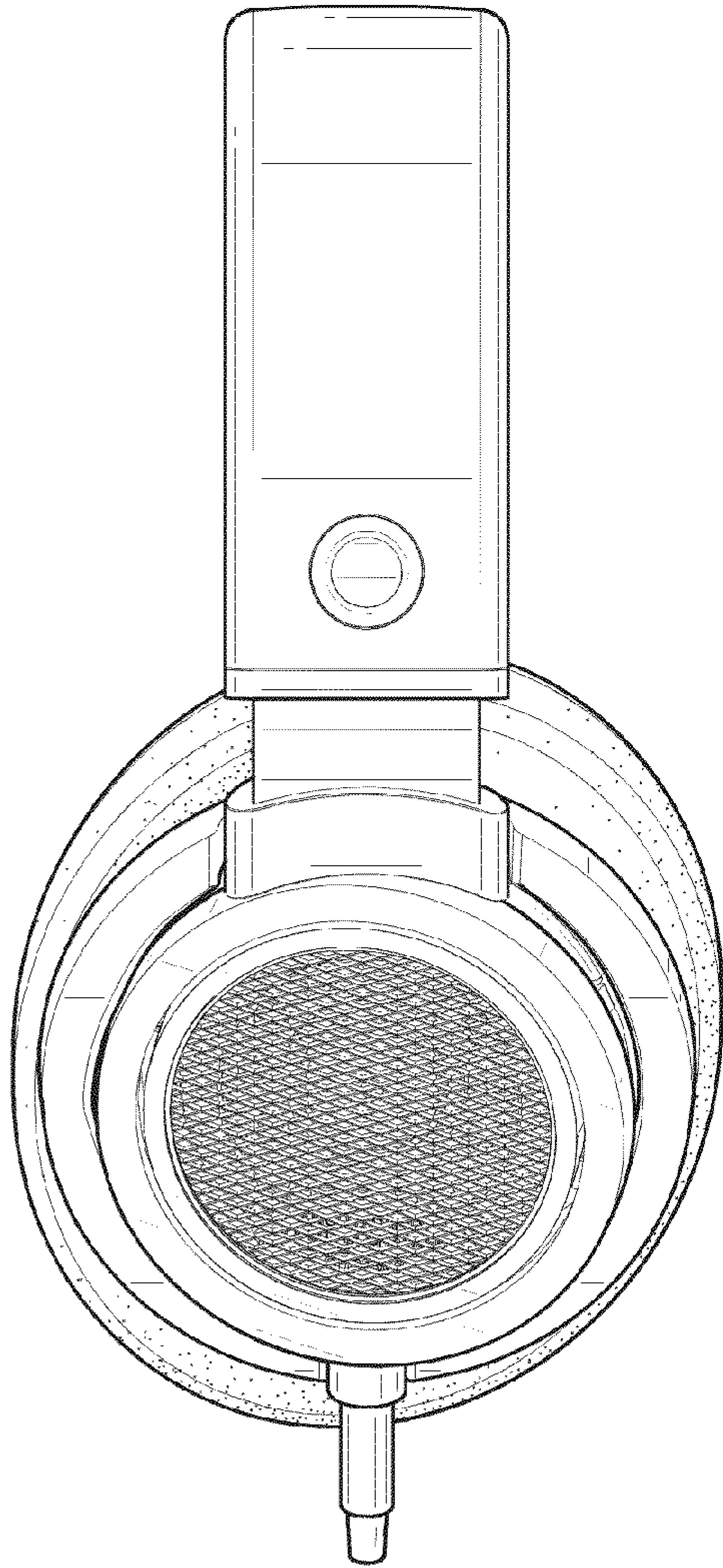


FIG. 4

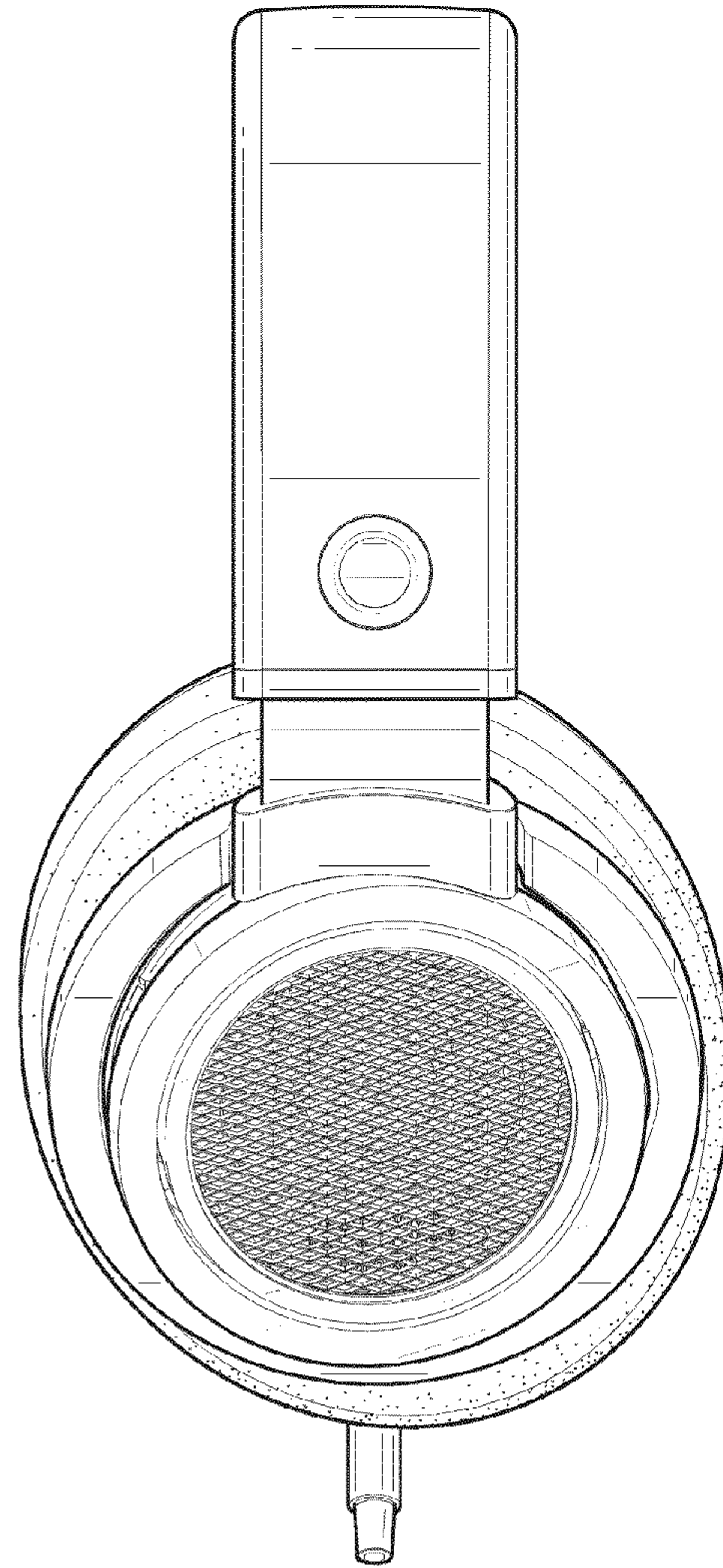


FIG. 5

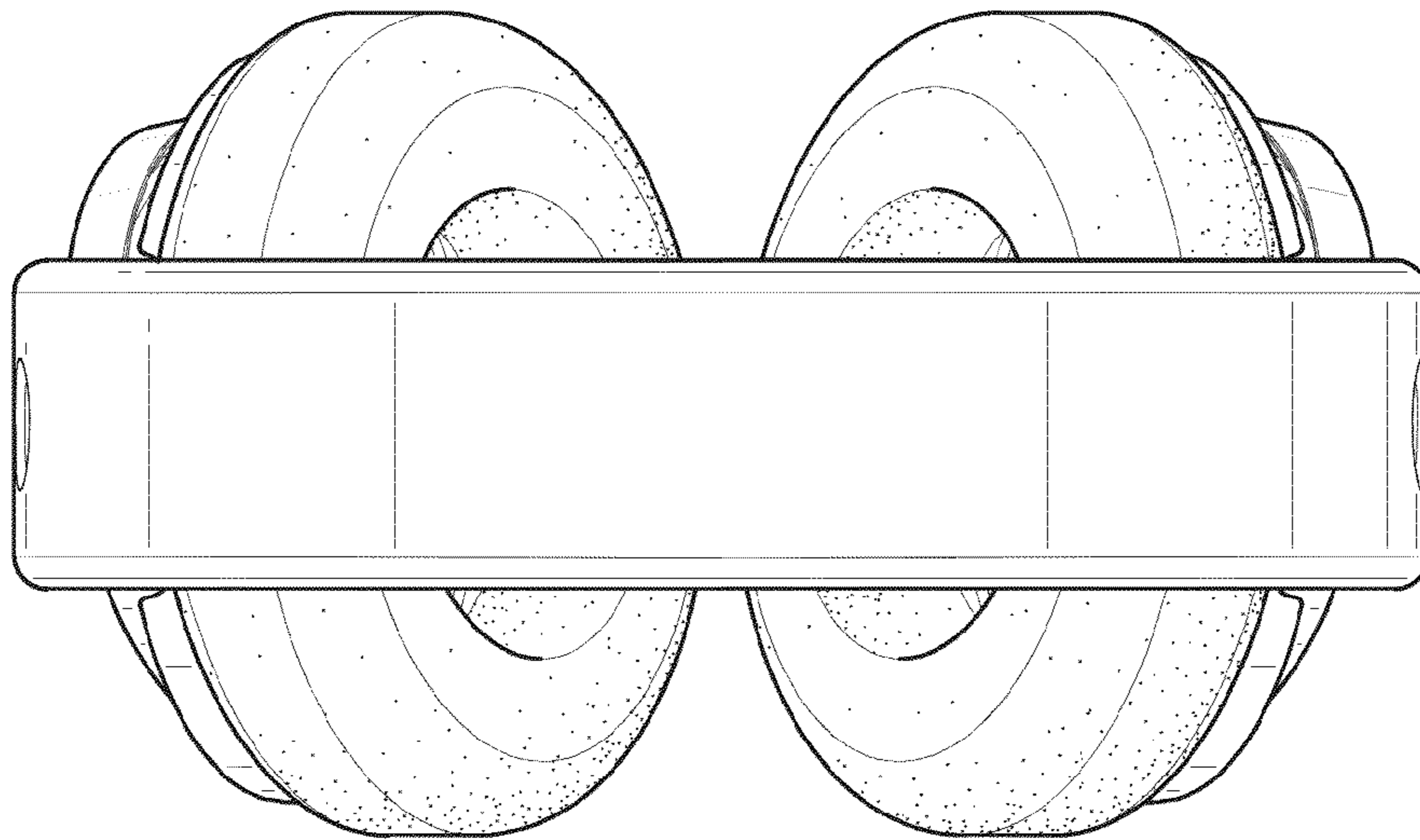


FIG. 6

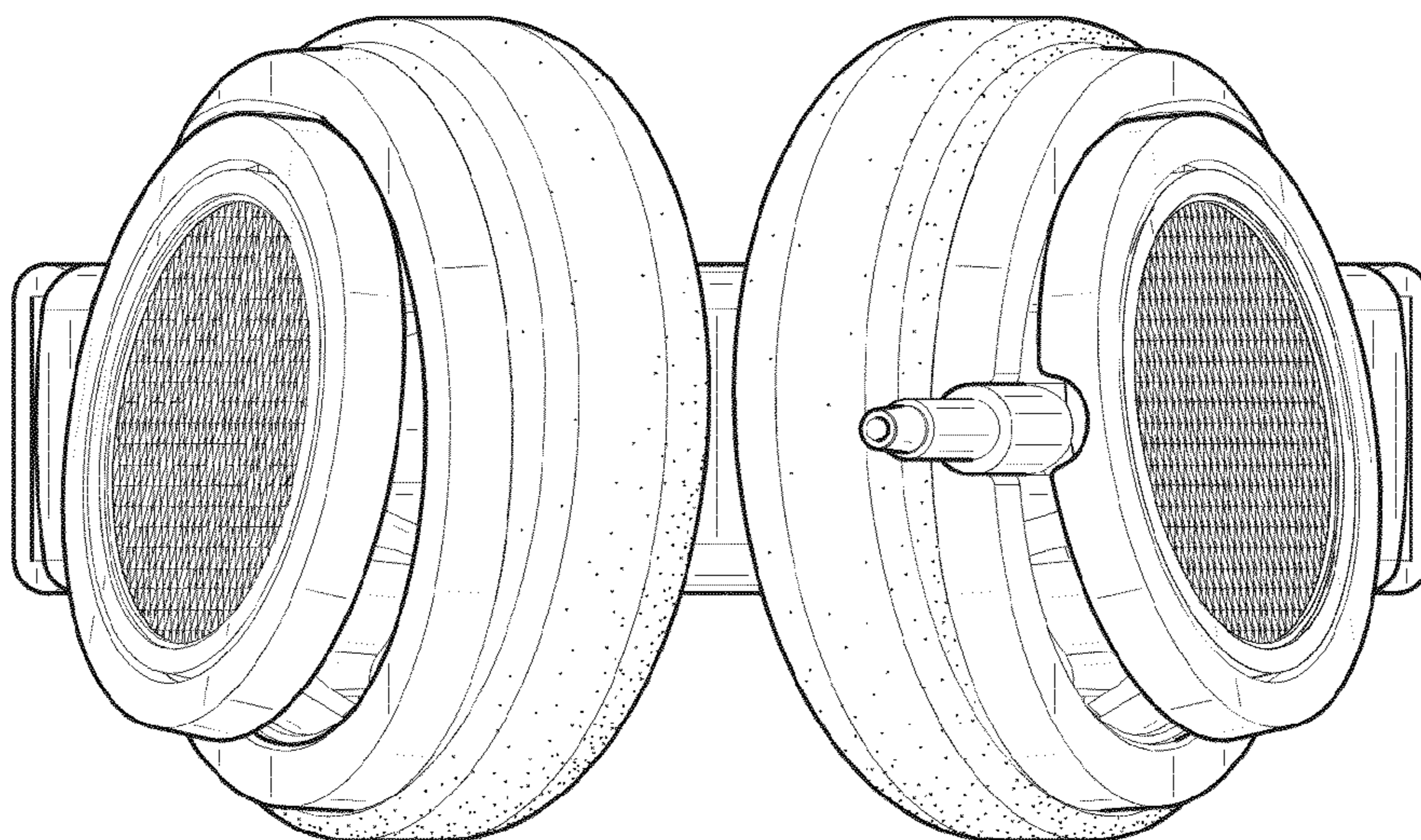


FIG. 7